HYCLEANSE® HTFG

Entec Polymers - Thermoplastic

Wednesday, November 6, 2019

General Information

Product Description

HyCleanse HTFG Purge contains several proprietary additives that are essential in the purging process of high temperatures resins and was created to be the least cost prohibitive high temperature purge compound on the market today. HyCleanse HTFG Purge can be used directly without any mixing necessary to clean most plastic equipment during color, and resin changes. The unique additives HyCleanse HTFG Purge, makes it possible to purge colors and degradation in less time than other purging compounds.

Features and Benefits:

HyCleanse-HTFG Purge is easy to use and no process changes are needed. Use at the normal resin processing temperature and RPM speed. No mixing is required. Also HyCleanse-HTFG Purge is not just a Mechanical purge.

Applications: Injection Molding - Pipe/Profile - Compounding

Types of Resins: PEEK, UHMW-HDPE, PEEK,PPS, PEK and PES

General	
Material Status	• Commercial: Active
Availability	• North America
Additive	• Proprietary
Uses	• Purging Compound
Agency Ratings	• FDA Unspecified Rating

ASTM & ISO Properties [1]

Additional Information	Nominal Value	Unit
Temperature Range	550 to 750	°F

Notes

[1] Typical properties: these are not to be construed as specifications.